

Inventor: Yoshiro IWASA Atty. Ref.: 9319S-000666

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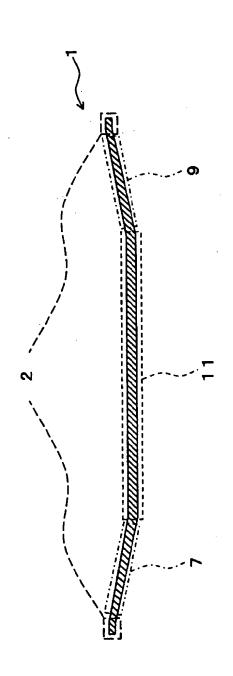
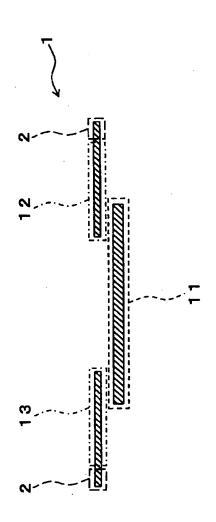
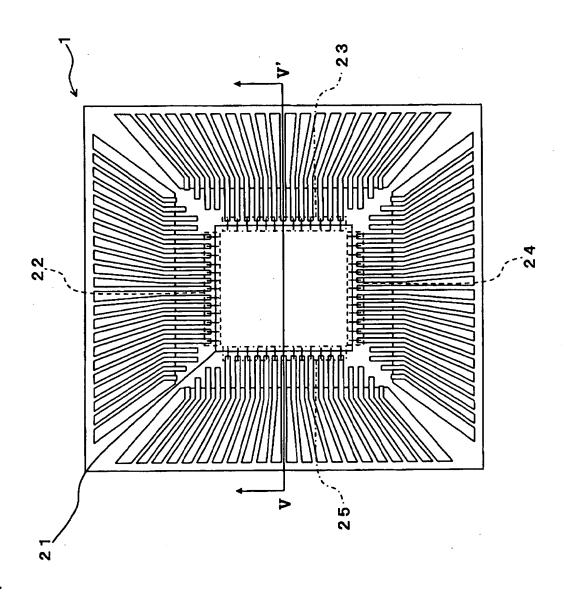


FIG.2

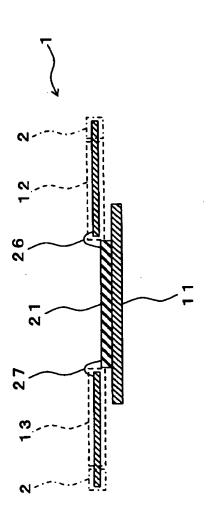


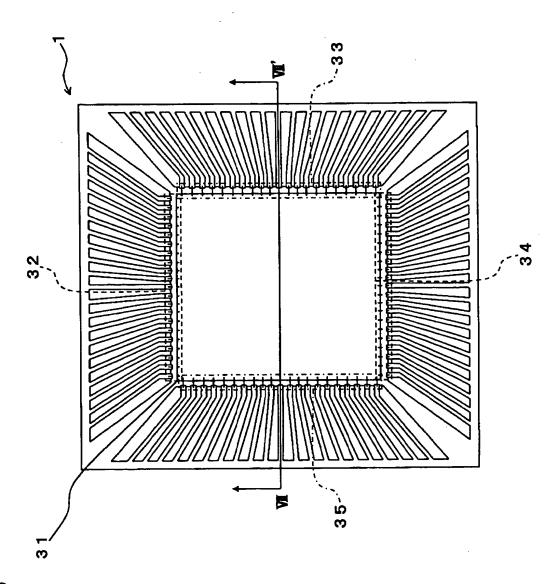
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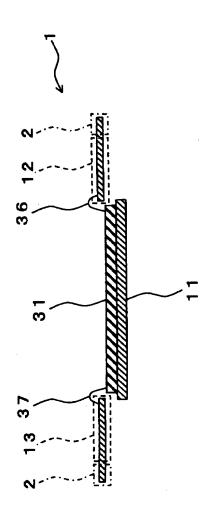


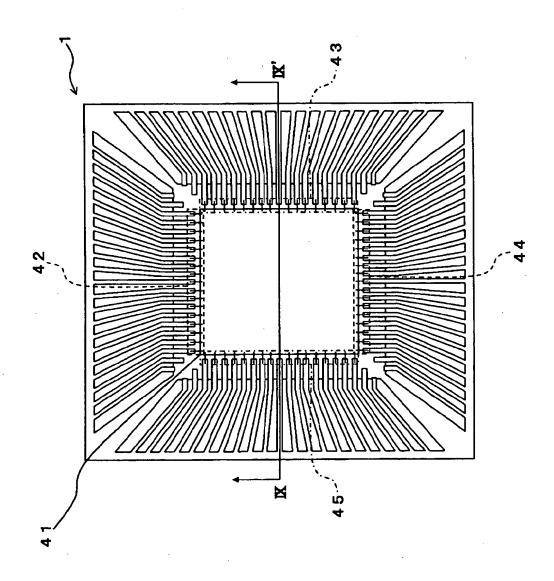
F16.4

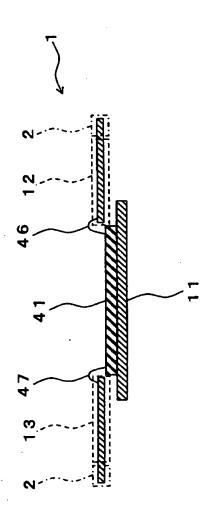




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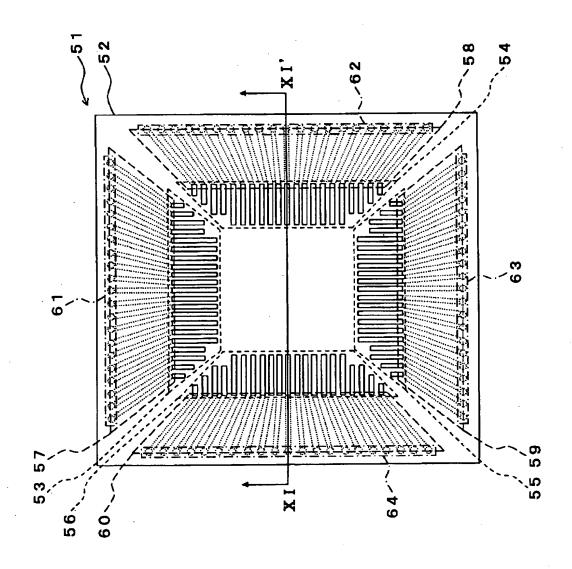


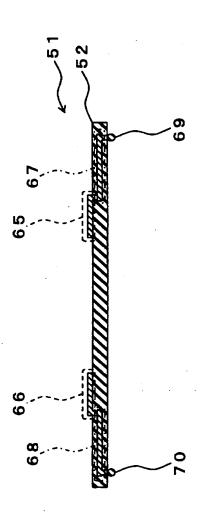




Title: LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE, METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE Inventor: Yoshiro IWASA Atty. Ref.: 9319S-000666

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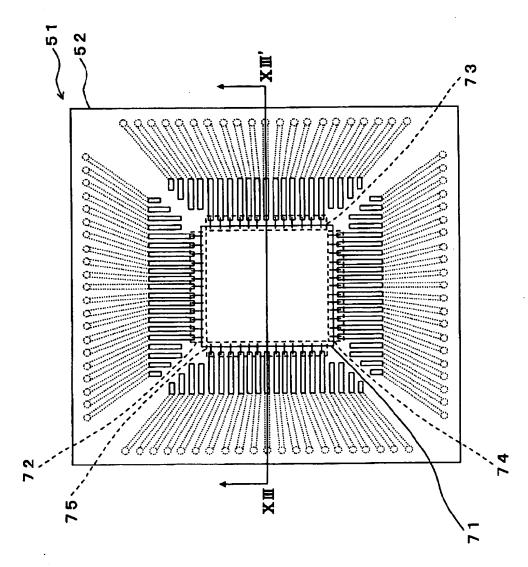


FIG. 12

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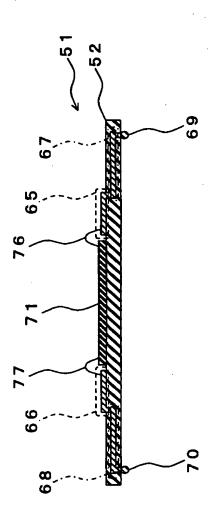


FIG. 13

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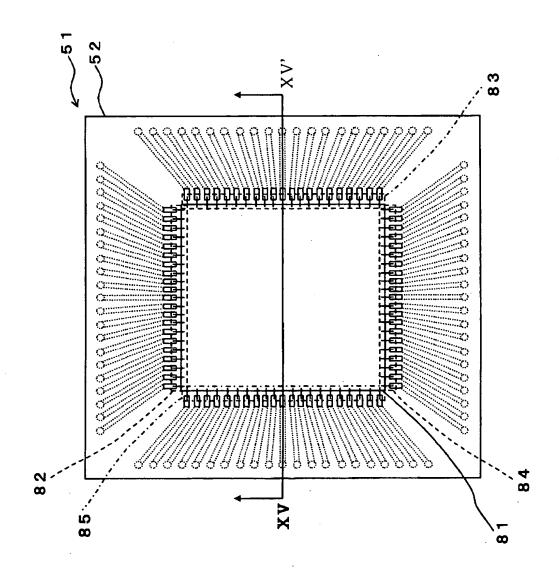
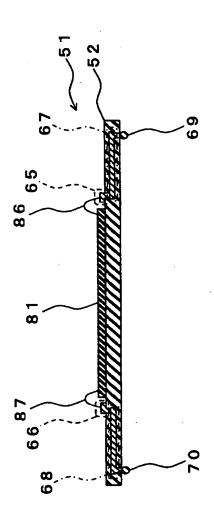
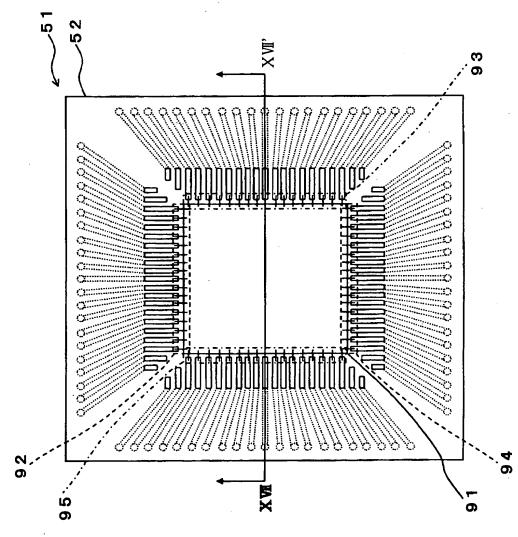


FIG.14

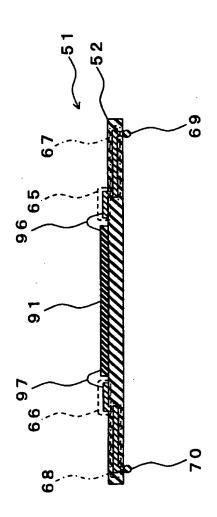


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